

SOT841-2

plastic thermal enhanced thin quad flat package; 80 leads;
body 12 x 12 x 1 mm; exposed die pad

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFP80
Package type industry code	HTQFP80
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	21-4-2004

Table 1. Package summary

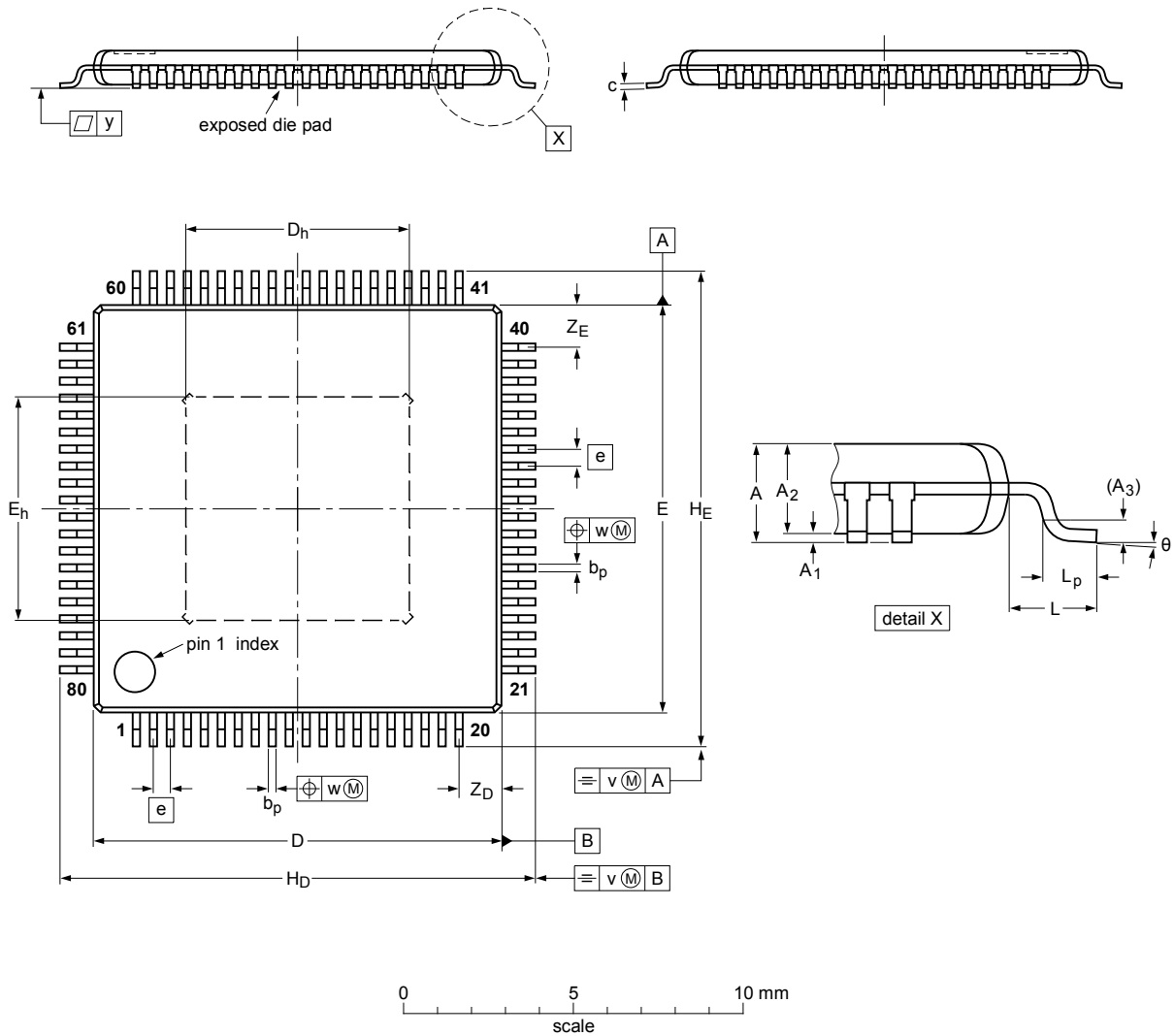
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.95	-	1	1.05	mm
n ₂	actual quantity of termination	-	-	80	-	



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2. Package outline

HTQFP80: plastic thermal enhanced thin quad flat package; 80 leads; body 12 x 12 x 1 mm; exposed die pad SOT841-2



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	1.2	0.15 0.05	1.05 0.95	0.25	0.27 0.17	0.20 0.09	12.1 11.9	6.65 6.55	12.1 11.9	6.65 6.55	0.5	14.15 13.85	14.15 13.85	1	0.75 0.45	0.2	0.08	0.1	1.45 1.05	1.45 1.05	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT841-2		MS-026				04-04-21

Fig. 1. Package outline HTQFP80 (SOT841-2)

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3. Soldering

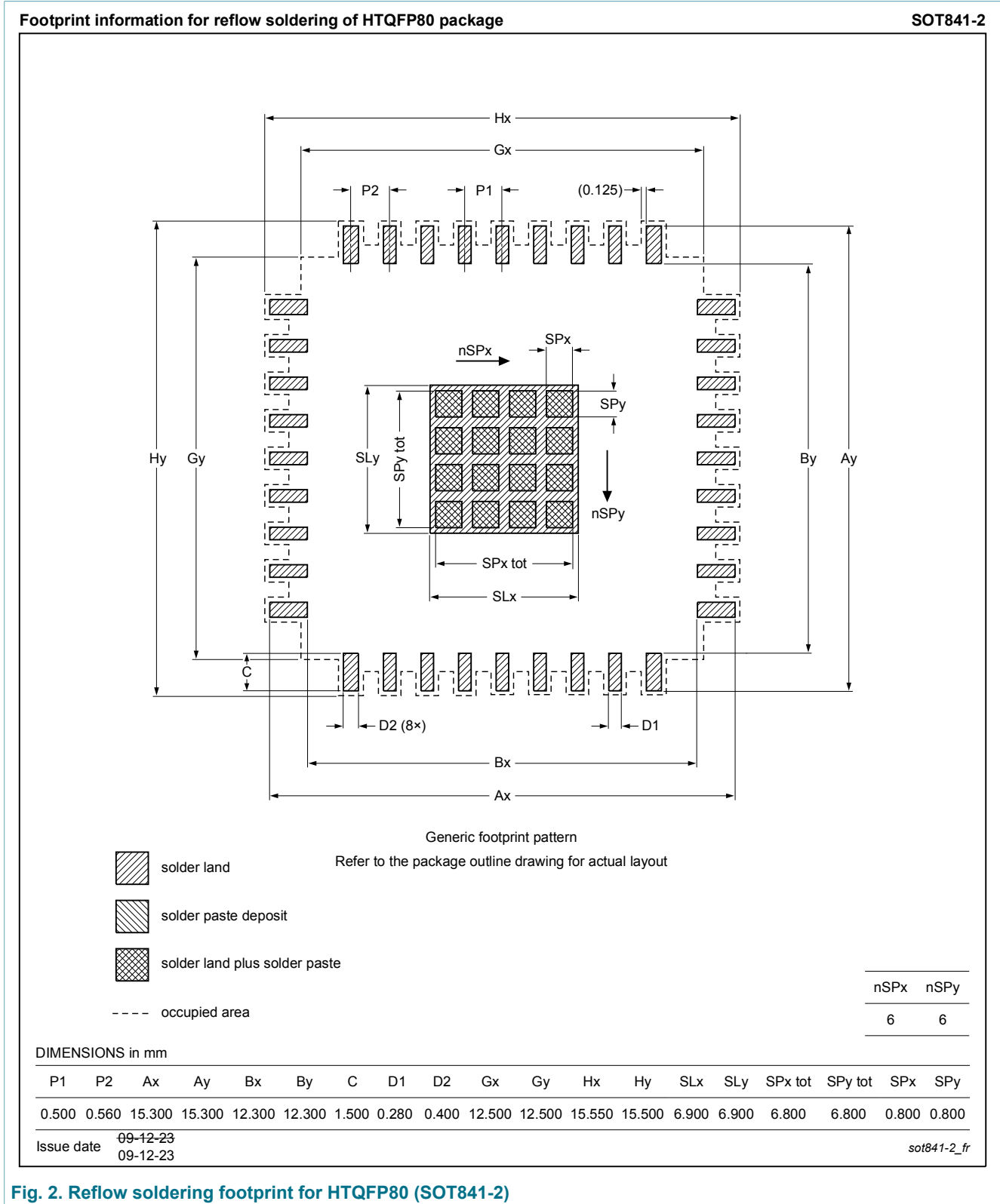


Fig. 2. Reflow soldering footprint for HTQFP80 (SOT841-2)

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4. Legal information

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